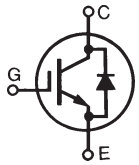
IXYS

Preliminary Technical Information

GenX3™ 600V IGBT IXGR72N60B3H1

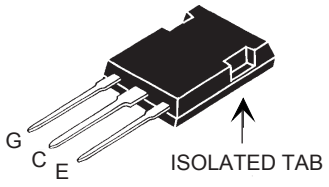
V_{CES} = 600V
I_{C110} = 40A
$V_{CE(sat)}$ ≤ 1.80V
$t_{fi(typ)}$ = 92ns

(Electrically Isolated Back Surface)



Medium Speed Low Vsat PT IGBT for 5-40 kHz Switching

ISOPLUS 247™



G = Gate C = Collector
E = Emitter

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (Limited by Leads)	75	A
I_{C110}	T_C = 110°C	40	A
I_{F110}	T_C = 110°C	34	A
I_{CM}	T_C = 25°C, 1ms	450	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 3Ω Clamped Inductive Load	I_{CM} = 240 V_{CE} ≤ 600	A V
P_C	T_C = 25°C	200	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
V_{ISOL}	50/60 Hz, RMS, t = 1minute I_{ISOL} < 1mA t = 20 seconds	2500 3000	V~ V~
F_C	Mounting Force	20..120/4.5..27	N/lb
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6mm (0.062 in.) from Case for 10s	260	°C
Weight		5	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V T_J = 125°C			300 5	μA mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 60A, V_{GE} = 15V, Note 1 I_C = 120A		1.50 1.75	1.80	V V

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V Electrical Isolation
- Optimized for Low Conduction and Switching Losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- DC Choppers
- AC Motor Speed Control
- DC Servo and Robot Drives

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 50A, V_{CE} = 10V, Note 1	45	76		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		6800		pF
C_{oes}			576		pF
C_{res}			80		pF
Q_g	I_C = 60A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		225		nC
Q_{ge}			40		nC
Q_{gc}			82		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		31		ns
t_{ri}			33		ns
E_{on}	I_C = 50A, V_{GE} = 15V		1.4		mJ
$t_{d(off)}$	V_{CE} = 480V, R_G = 3Ω		152	240	ns
t_{fi}			92	150	ns
E_{off}			1.0	2.0	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		29		ns
t_{ri}			34		ns
E_{on}	I_C = 50A, V_{GE} = 15V		2.7		mJ
$t_{d(off)}$	V_{CE} = 480V, R_G = 3Ω		228		ns
t_{fi}			142		ns
E_{off}			2.2		mJ
R_{thJC}				0.62	°C/W
R_{thCS}			0.15		°C/W

Reverse Diode (FRED)

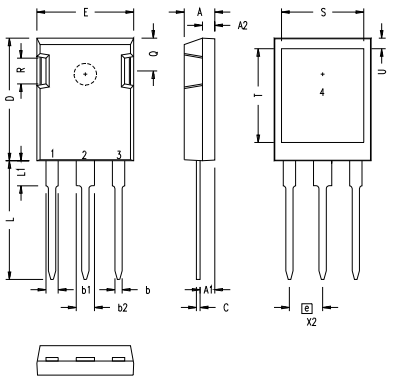
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 60A, V_{GE} = 0V, Note 1		1.6	2.0	V
	T_J = 150°C		1.4	1.8	V
I_{RM}	I_F = 60A, V_{GE} = 0V, T_J = 100°C $-di_F/dt$ = 200A/μs, V_R = 300V		8.3		A
t_{rr}	I_F = 60A, -di/dt = 200A/μs, V_R = 300V, T_J = 100°C		140		ns
R_{thJC}				0.8	°C/W

Note 1. Pulse Test, t ≤ 300μs; Duty Cycle, d ≤ 2%.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

ISOPLUS247 (IXGR) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.084	1.91	2.13
b2	.115	.123	2.92	3.12
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.800	19.81	20.32
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03

1 – GATE
2 – DRAIN (COLLECTOR)
3 – SOURCE (EMITTER)
4 – NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

Fig. 1. Output Characteristics @ 25ºC

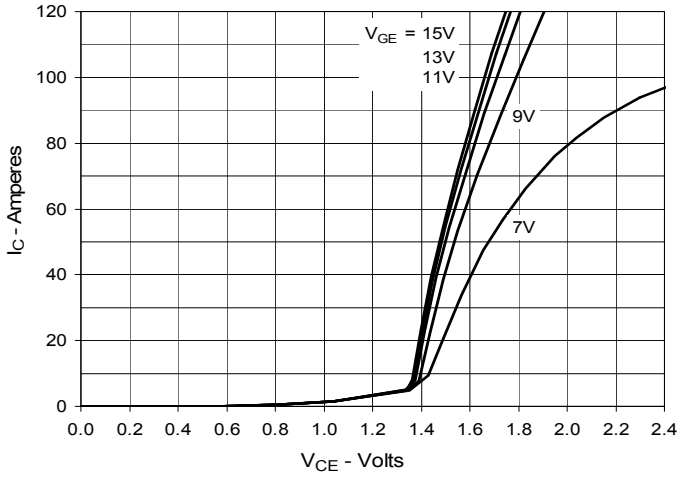


Fig. 2. Extended Output Characteristics @ 25ºC

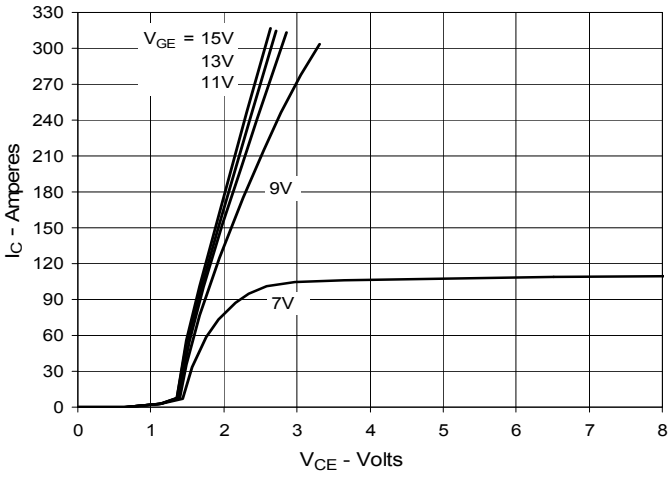


Fig. 3. Output Characteristics @ 125ºC

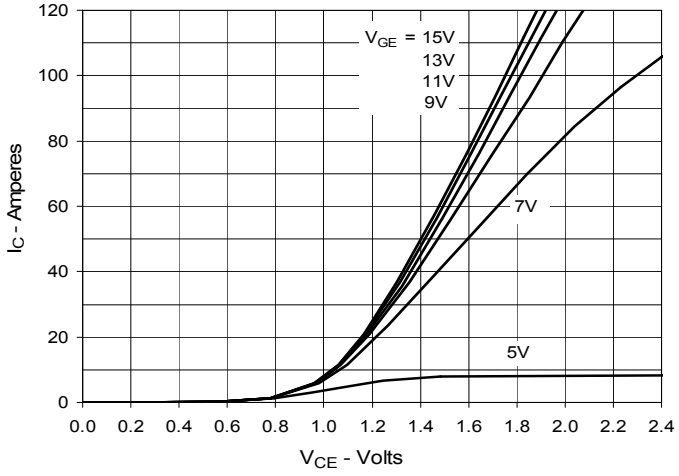


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

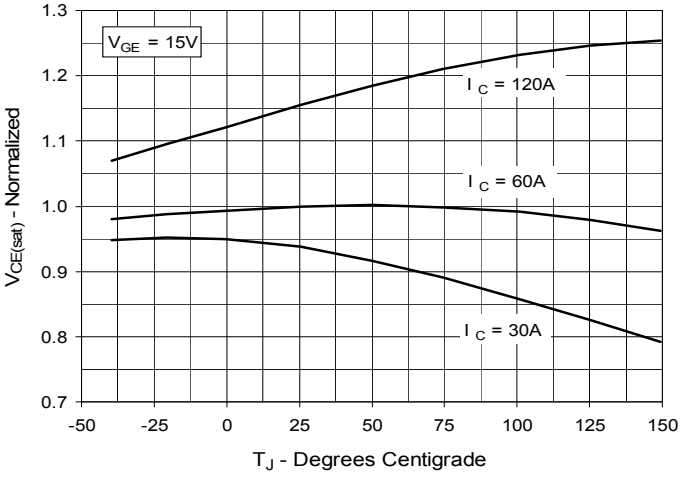


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

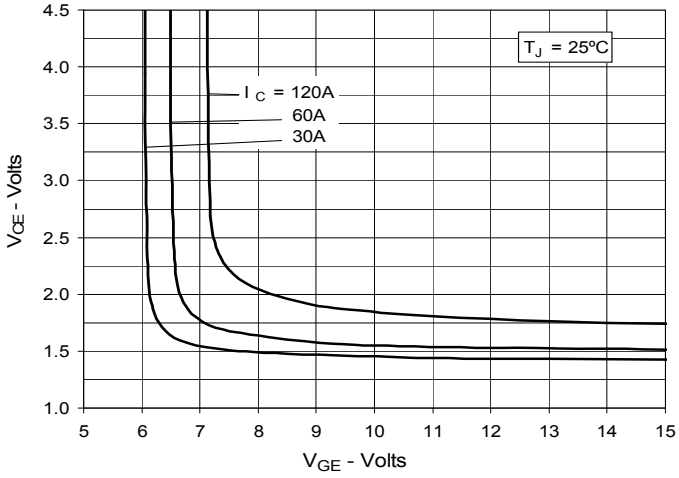


Fig. 6. Input Admittance

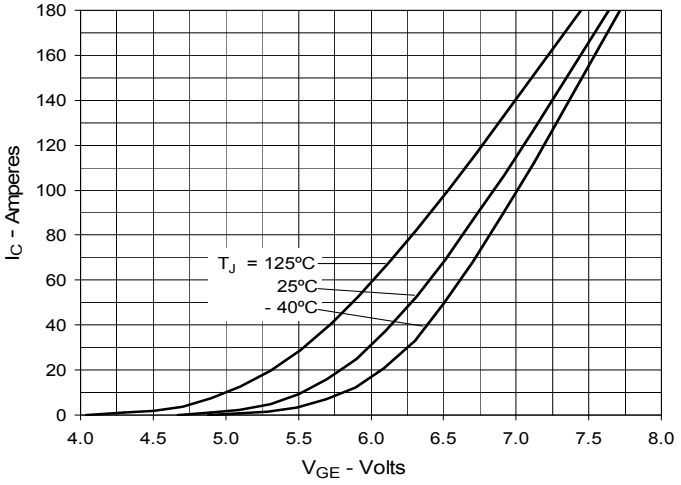


Fig. 7. Transconductance

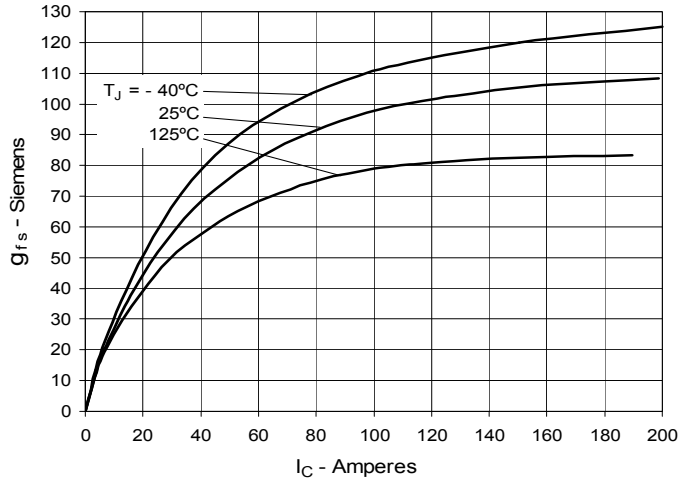


Fig. 8. Gate Charge

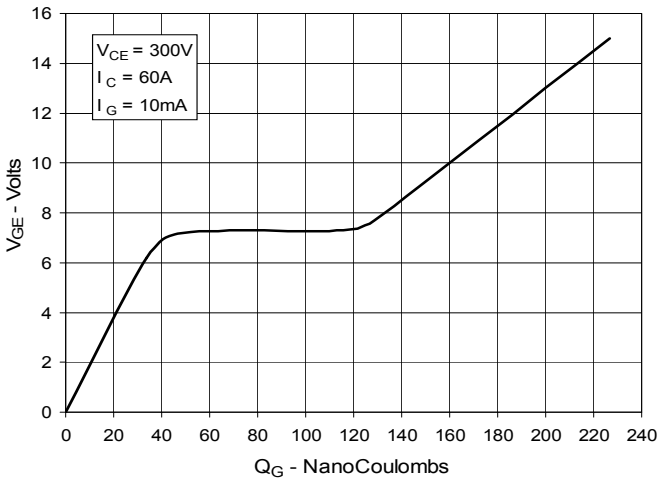


Fig. 9. Capacitance

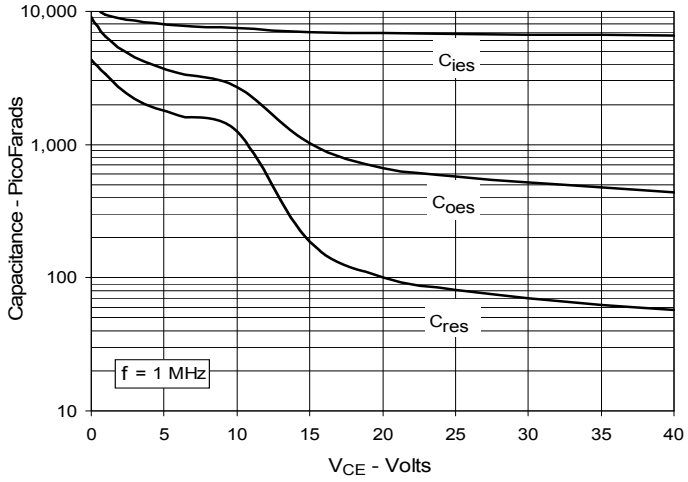


Fig. 10. Reverse-Bias Safe Operating Area

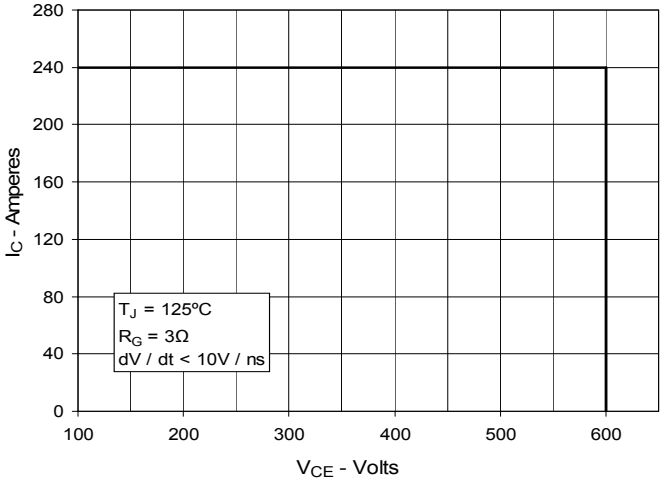


Fig. 11. Maximum Transient Thermal Impedance

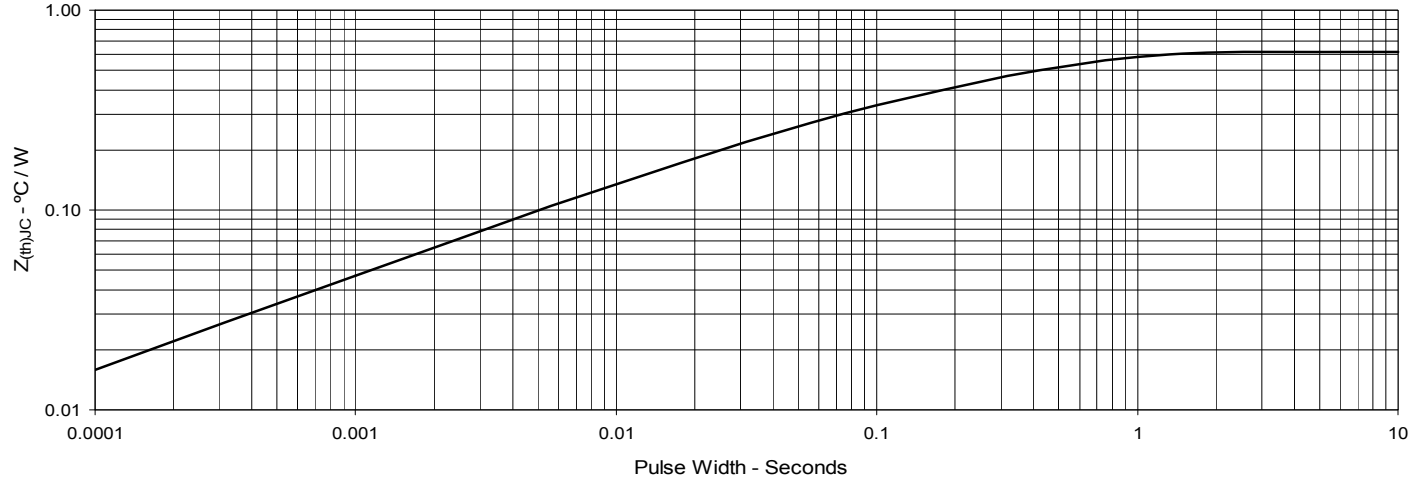


Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

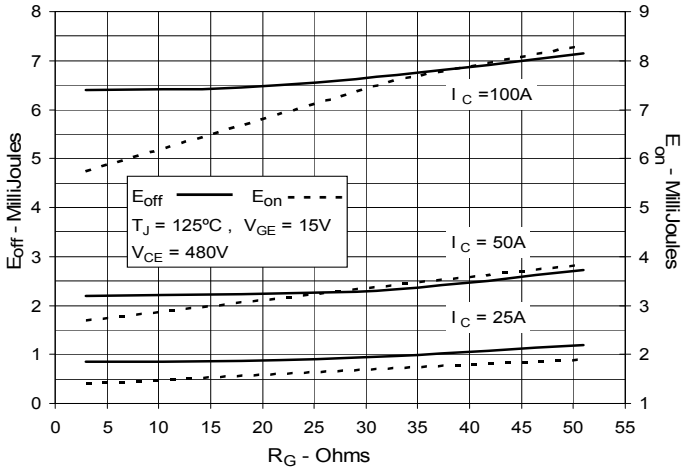


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

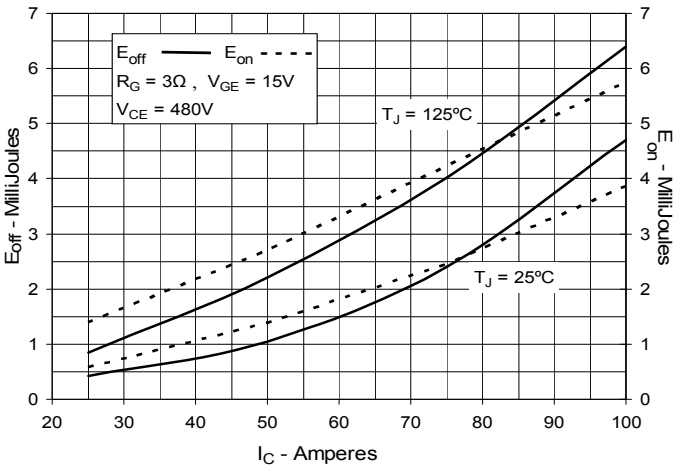


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

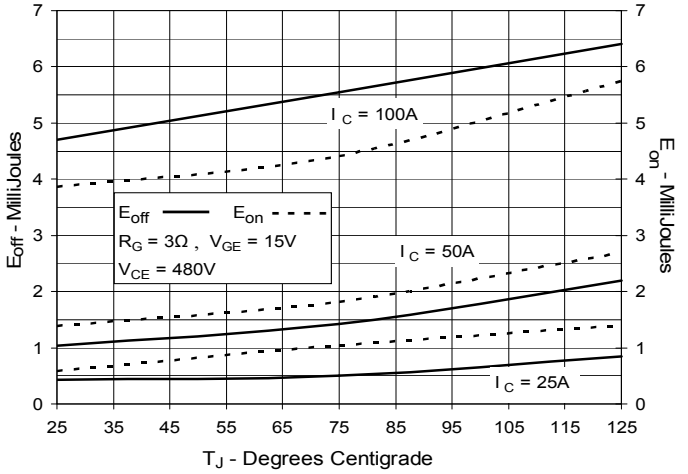


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

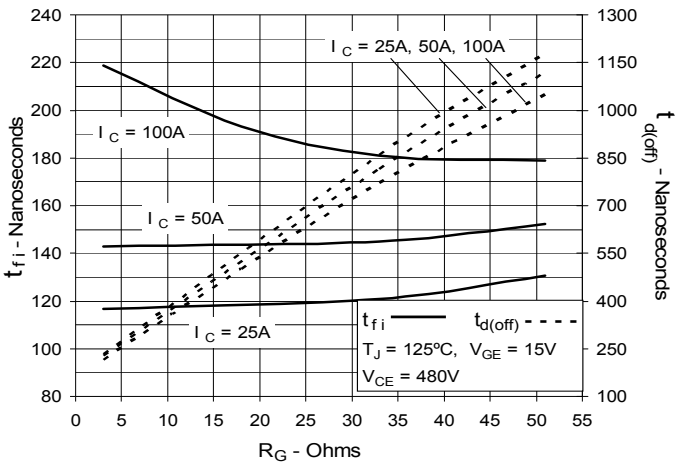


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

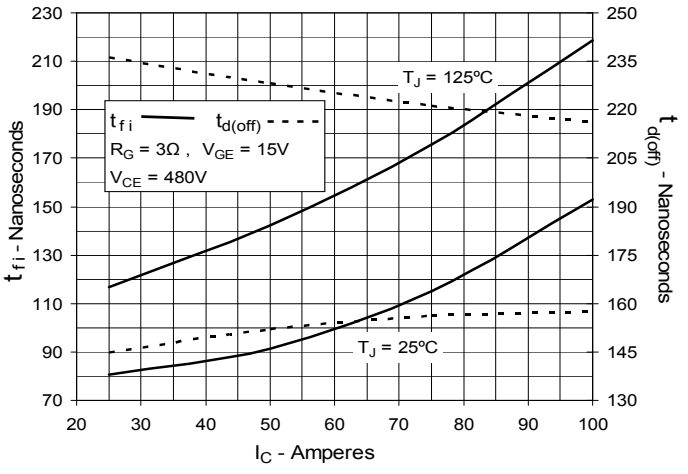


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

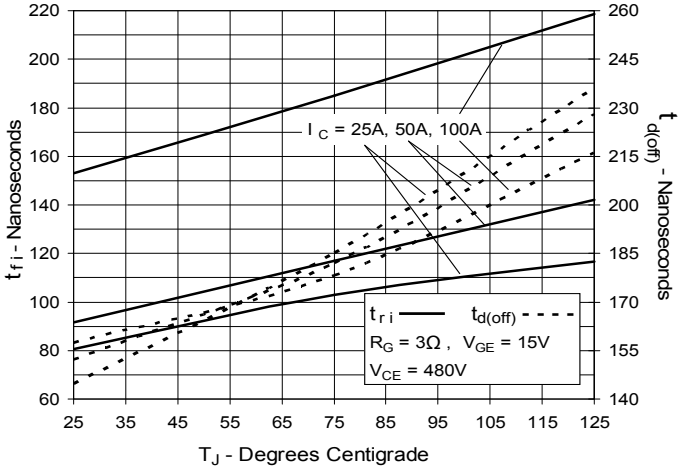


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

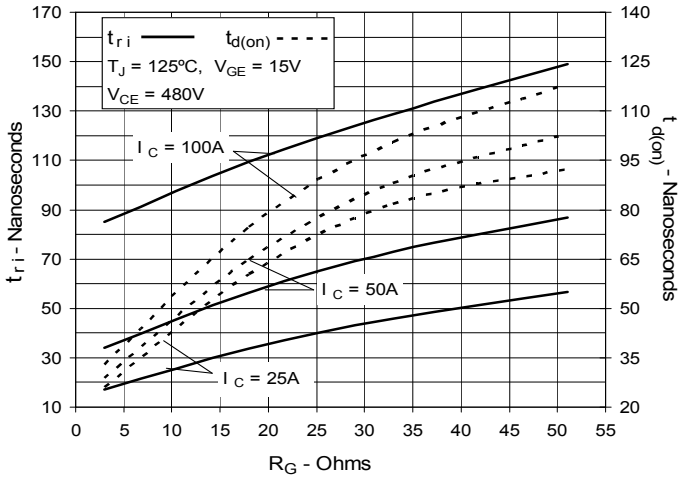


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

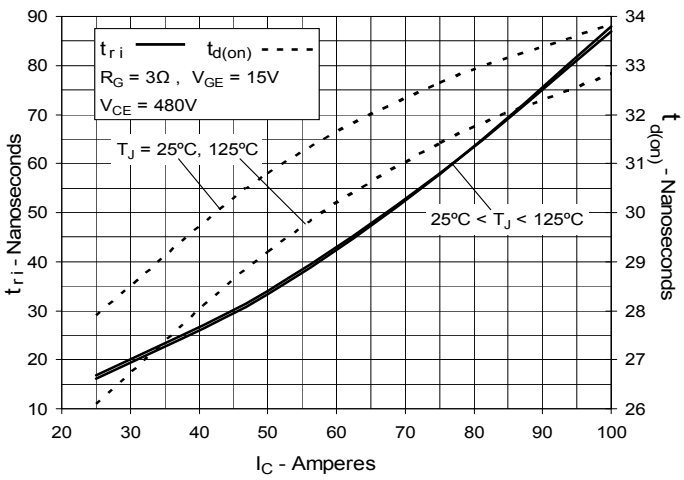
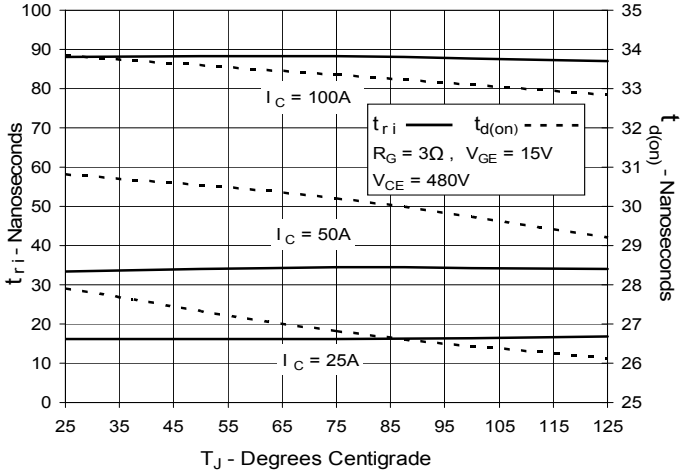


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



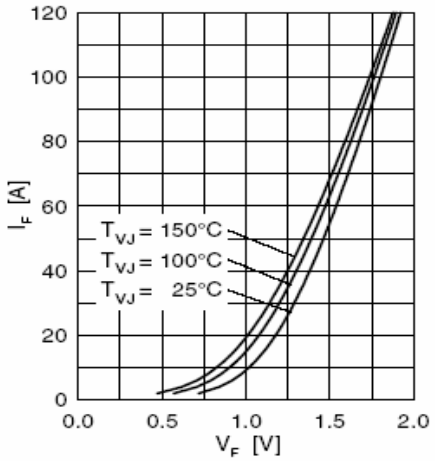


Fig. 21 Forward Current I_F vs. V_F

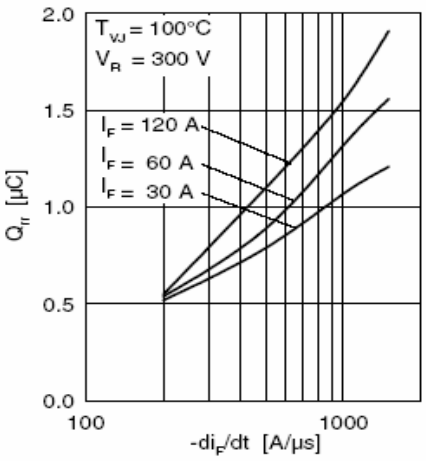


Fig. 22 Typ. Reverse Recovery Charge Q_{rr}

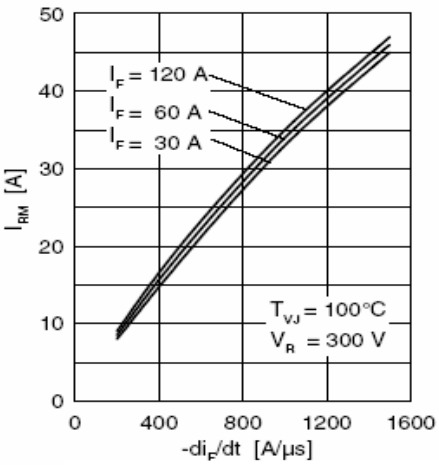


Fig. 23 Typ. Peak Reverse Current I_{RM}

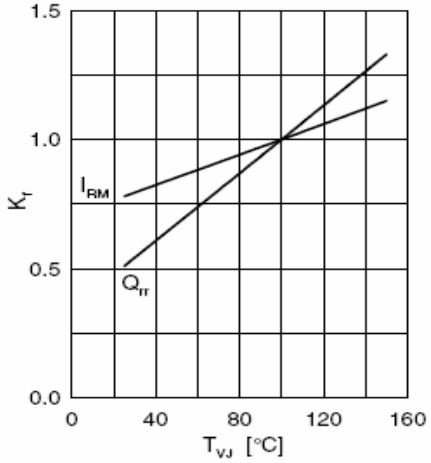


Fig. 24 Typ. Dynamic Parameters Q_{rr}, I_{RM}

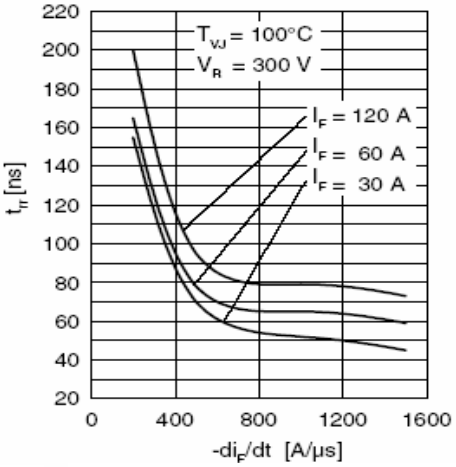


Fig. 25 Typ Recovery Time t_{rr}

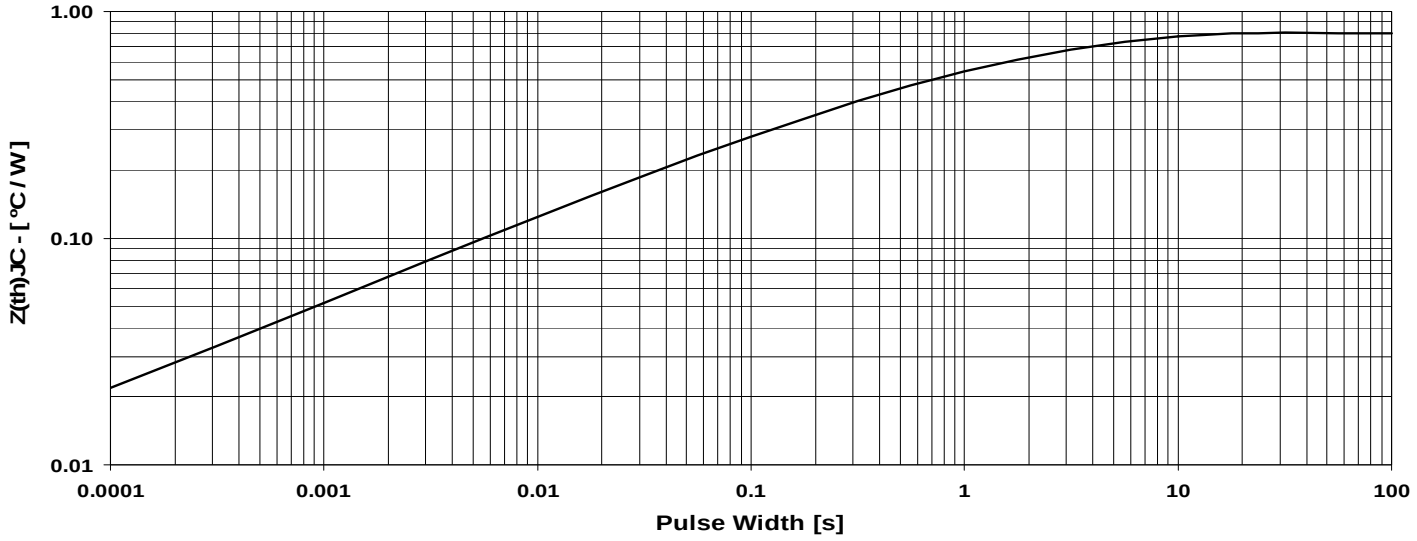


Fig. 26 Maximum Transient Thermal Impedance Junction to Case (for Diode)

LifeElectronics
Живое партнерство

ООО «ЛайфЭлектроникс» **“LifeElectronics” LLC**

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

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- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
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- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

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- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
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